

IN THE CLAIMS

1. (Currently Amended) A method of manufacturing a member pattern having a patterned member on a substrate, comprising:

a first exposure step of exposing a desired region of a negative type photosensitive material applied to the substrate to light from a first direction;

a second exposure step of exposing the desired region of the negative type photosensitive material to light from a second direction opposite to said first direction;

a development step of performing development after said exposure steps to form a precursor pattern of said member; and

a step of baking said precursor pattern,

wherein said negative type photosensitive material is applied to extend over a member previously disposed on said substrate and said substrate.

2. (Canceled)

3. (Currently Amended) The method of manufacturing a member pattern according to Claim [[2]] 1, wherein the member previously disposed on said substrate has a higher optical reflectance than said substrate.

4. (Currently Amended) The method of manufacturing a member pattern according to Claim [[2]] 1, wherein the member previously disposed on said substrate is a

member that is formed in a process involving exposure, development and baking of a photosensitive material.

5. (Currently Amended) The method of manufacturing a member pattern according to Claim [[2]] 1, wherein the member previously disposed on said substrate has an overhanging part in the cross section thereof.

6. (Original) The method of manufacturing a member pattern according to Claim 1, wherein said patterned member is an insulating member, and said insulating member has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulating member interposed therebetween.

7. (Original) A method of manufacturing a member pattern having a patterned member on a substrate, comprising:

a first exposure step of exposing a desired region of a negative type photosensitive material applied to the substrate to light from a first direction;

a development step of performing development after said first exposure step to form a precursor pattern of said member;

a second exposure step of exposing the precursor pattern of said member to light from a second direction opposite to said first direction; and

a step of baking said precursor pattern after said second exposure step.

8. (Original) The method of manufacturing a member pattern according to Claim 7, wherein said negative type photosensitive material is applied to extend over a member previously disposed on said substrate and said substrate.

9. (Original) The method of manufacturing a member pattern according to Claim 8, wherein the member previously disposed on said substrate has a higher optical reflectance than said substrate.

10. (Original) The method of manufacturing a member pattern according to Claim 8, wherein the member previously disposed on said substrate is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

11. (Original) The method of manufacturing a member pattern according to Claim 8, wherein the member previously disposed on said substrate has an overhanging part in the cross section thereof.

12. (Original) The method of manufacturing a member pattern according to Claim 7, wherein said patterned member is an insulating member, and said insulating member has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulating member interposed therebetween.

13. (Original) A method of manufacturing a wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator,

wherein a process of forming said insulator comprises: a first exposure step of exposing a desired region of a negative type photosensitive insulating material to light from a first direction, the negative type photosensitive insulating material being applied to extend over said substrate and the first wiring disposed on the substrate; a second exposure step of exposing the desired region of the negative type photosensitive insulating material to light from a second direction opposite to said first direction; a step of performing development after said exposure steps to form a precursor pattern of said insulator; and a step of baking the precursor pattern of said insulator.

14. (Original) The method of manufacturing a wiring structure according to Claim 13, wherein said first wiring is a member which has a higher optical reflectance than said substrate.

15. (Original) The method of manufacturing a wiring structure according to Claim 13, wherein said first wiring is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

16. (Original) The method of manufacturing a wiring structure according to Claim 13, wherein said first wiring has an overhanging part in the cross section thereof.

17. (Original) The method of manufacturing a wiring structure according to Claim 13, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulator interposed therebetween.

18. (Original) A method of manufacturing an electron source having a wiring structure and an electron emitting element connected to said wiring structure, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is manufactured according to the method in Claim 13.

19. (Original) A method of manufacturing an image display device having a wiring structure, an electron emitting element connected to said wiring structure and an image display member for displaying an image by irradiation with electrons from said electron emitting element, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is manufactured according to the method in Claim 13.

20. (Original) A method of manufacturing a wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator,

wherein a process of forming said insulator comprises: a first exposure step of exposing a desired region of a negative type photosensitive insulating material to light from a first direction, the negative type photosensitive insulating material being applied to extend over said substrate and the first wiring disposed on the substrate; a step of performing development after said first exposure step to form a precursor pattern of said insulator; a second exposure step of exposing the precursor pattern of said insulator to light from a second direction opposite to said first direction; and a step of baking the precursor pattern after said second exposure step.

21. (Original) The method of manufacturing a wiring structure according to Claim 20, wherein said first wiring is a member which has a higher optical reflectance than said substrate.

22. (Original) The method of manufacturing a wiring structure according to Claim 20, wherein said first wiring is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

23. (Original) The method of manufacturing a wiring structure according to Claim 20, wherein said first wiring has an overhanging part in the cross section thereof.

24. (Original) The method of manufacturing a wiring structure according to Claim 20, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulator interposed therebetween.

25. (Original) A method of manufacturing an electron source having a wiring structure and an electron emitting element connected to said wiring structure, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is manufactured according to the method in Claim 20.

26. (Original) A method of manufacturing an image display device having a wiring structure, an electron emitting element connected to said wiring structure and an image display member for displaying an image by irradiation with electrons from said electron emitting element, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is manufactured in the method according to Claim 20.